Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: *Required Field*	

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2023-11-07
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	AMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by Antonella Lanzafame
Date: 2023.11.07 10:47:26 +01:00

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
	1N0J*MY3CADQ	A	Z7GA	2023-11-07
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	260	mg	Each	ECOPACK® 3

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
3	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	,

Package designator	Package size	Number of instances	Shape	
qfn	10 x 10	72	Flat	
Comment				
Comment	B0DB VFQFPN 10X10X0.95 72L PITCH 05; MD valid for CP: STSPIN32G0602Q,STSPIN32G0602QTR.			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	**Description**

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	**Description**

QueryList : California Prop65 list, dated 11th Aug 2023			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	**amount in product (mg)**	**Application**	**ppm in product**
Nickel	5.198	alloy	19992

QueryList :Customer	Response
QUERY	**Response**

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				Response
QUERY				**Response**
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hazardous substance				
Lead (Pb)	**Cadmium (Cd)**	**Mercury (Hg)**	**Hexavalent Chromium (Cr VI)**	**PBB & PBDE**
O	O	O	O	O

QueryList : REACH-14th June 2023				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material

QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	**Gold, Tungsten,**

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

Stockholm Convention Persistent Organic Pollutants	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	true

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**1N0J*MY3CADQ**		260.0013		5000003.0	1000006.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	M-011 Other inorganic materials	6.339	mg	supplier	die	Silicon(Si)	7440-21-3		6.134	mg	967661	23592
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.028	mg	4417	108
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.004	mg	631	15
				supplier	metallisation	Gold(Au)	7440-57-5		0.009	mg	1420	35
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.017	mg	2682	65
				supplier	metallisation	Tungsten(W)	7440-33-7		0.037	mg	5837	142
				supplier	metallisation	Vanadium(V)	7440-62-2		0.001	mg	158	4
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.010	mg	1578	38
				supplier	passivation	Silicon oxide	7631-86-9		0.099	mg	15618	381
Leadframe	M-004 Copper and its alloys	117.740	mg	supplier	alloy	Copper	7440-50-8		111.425	mg	946367	428558
				supplier	alloy	Silicon	7440-21-3		0.839	mg	7126	3227
				supplier	alloy	Magnesium	7439-95-4		0.203	mg	1724	781
				supplier	alloy	Nickel	7440-02-0		5.181	mg	44004	19927
				supplier	alloy	Palladium	7440-05-3		0.058	mg	493	223
				supplier	alloy	Gold	7440-57-5		0.035	mg	297	135
Die attach	M-011 Other inorganic materials	4.340	mg	supplier	glue	Silver	7440-22-4		3.537	mg	815000	13604
				supplier	glue	(Octahydro-4,7-methano-1 H-indenediyl)bis(meth	42594-17-2		0.260	mg	60000	1002
				supplier	glue	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacr	7534-94-3		0.260	mg	60000	1002
				supplier	glue	Isobornyl acrylate	5888-33-5		0.260	mg	60000	1002
				supplier	glue	2-(3,4-Epoxycyclohexyl)ethyltrimethoxysilane	3388-04-3		0.022	mg	5000	83
Bonding wires	M-004 Copper and its alloys	6.245	mg	supplier	wire	Copper	7440-50-8		6.027	mg	965000	23180
	0			supplier	wire	Palladium	7440-05-3		0.156	mg	24990	600
	M-008 Precious metals			supplier	wire	Gold	7440-57-5		0.062	mg	10000	240
Encapsulation	M-011 Other inorganic materials	125.336	mg	supplier	mold compound	Epoxy Resin	Trade secret		6.018	mg	48019	23148
				supplier	mold compound	Phenol Resin	Trade secret		3.250	mg	25930	12500
				supplier	mold compound	Silica (Amorphous)A	60676-86-0		109.688	mg	875151	421877
				supplier	mold compound	Silica (Amorphous)B	7631-86-9		6.018	mg	48019	23148